

Docket No. 279784US2PCT



JAN 19 2006  
U.S. PATENT AND TRADEMARK OFFICE  
PCT

\*IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

IN RE APPLICATION OF: Takamaro KIKKAWA, et al.

SERIAL NO: 10/553,994

GAU:

FILED: October 20, 2005

EXAMINER:

FOR: SEMICONDUCTOR DEVICE

INFORMATION DISCLOSURE STATEMENT UNDER 37 CFR 1.97

COMMISSIONER FOR PATENTS  
ALEXANDRIA, VIRGINIA 22313

SIR:

Applicant(s) wish to disclose the following information.

REFERENCES

- The applicant(s) wish to make of record the references listed on the attached form PTO-1449. Copies of the listed references are attached, where required, as are either statements of relevancy or any readily available English translations of pertinent portions of any non-English language references.
- A check or credit card payment form is attached in the amount required under 37 CFR §1.17(p).

RELATED CASES

- Attached is a list of applicant's pending application(s), published application(s) or issued patent(s) which may be related to the present application. In accordance with the waiver of 37 CFR 1.98 dated September 21, 2004, copies of the cited pending applications are not provided. Cited published and/or issued patents, if any, are listed on the attached PTO form 1449.
- A check or credit card payment form is attached in the amount required under 37 CFR §1.17(p).

CERTIFICATION

- Each item of information contained in this information disclosure statement was first cited in any communication from a foreign patent office in a counterpart foreign application not more than three months prior to the filing of this statement.
- No item of information contained in this information disclosure statement was cited in a communication from a foreign patent office in a counterpart foreign application or, to the knowledge of the undersigned, having made reasonable inquiry, was known to any individual designated in 37 CFR §1.56(c) more than three months prior to the filing of this statement.

DEPOSIT ACCOUNT

- Please charge any additional fees for the papers being filed herewith and for which no check or credit card payment is enclosed herewith, or credit any overpayment to deposit account number 15-0030. A duplicate copy of this sheet is enclosed.

Respectfully submitted,

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03/21/2007 1:27:00

ALL REFERENCES CONSIDERED EXCEPT WHERE LINED THROUGH. /H.Le./



10553994 - GAU: 2821

SHEET 1 OF 1

Form PTO 1449  
(Modified)U.S. DEPARTMENT OF COMMERCE  
PATENT AND TRADEMARK OFFICEATTY DOCKET NO.  
279784US2PCTSERIAL NO.  
10/553,994

## LIST OF REFERENCES CITED BY APPLICANT

## APPLICANT

Takamaro KIKKAWA, et al.

## FILING DATE

October 20, 2005

## GROUP

## U.S. PATENT DOCUMENTS

EXAMINER INITIAL		DOCUMENT NUMBER	DATE	NAME	CLASS	SUB CLASS	FILING DATE IF APPROPRIATE
	AA						
	AB						
	AC						
	AD						
	AE						
	AF						
	AG						
	AH						
	AI						
	AJ						
	AK						
	AL						
	AM						
	AN						

## FOREIGN PATENT DOCUMENTS

		DOCUMENT NUMBER	DATE	COUNTRY	TRANSLATION YES	NO
	AO	2001-326328	11/22/01	JP (with English abstract)		NO
	AP	2000-124406	04/28/00	JP (with English abstract)		NO
	AQ					
	AR					
	AS					
	AT					
	AU					
	AV					

## OTHER REFERENCES (Including Author, Title, Date, Pertinent Pages, etc.)

AW	RASHID A.B.M. Harun-ur et al., 'Interference Suppression of Wireless Interconnection in Si Integrated Antenna', Proceedings of the IEEE International Interconnect Technology Conference, Pages 173 to 175, 2002.
AX	FLOYD Brian A. et al., 'Intra-Chip Wireless Interconnect for Clock Distribution Implemented With Integrated Antennas, Receivers, and Transmitters', IEEE Journal of Solid-State Circuits, Vol. 37, No. 5, Pages 543 to 552, 2002.
AY	GUO Xiaolin et al., 'Propagation Layers for Intra-chip Wireless Interconnection Compatible with Packaging and Heat Removal', Symposium On VLSI Technology Digest of Technical Papers, Pages 36 to 37, 2002.
AZ	KIM Kihong et al., 'A Plane Wave Model Approach to Understanding Propagation in an Intra-chip Communication System', Antennas and Propagation Society International Symposium , Vol. 2, Pages 166-169, 2001

 Additional References sheet(s) attached

Examiner /Hoanganh Le/ Date Considered 09/28/2009

\*Examiner: Initial if reference is considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.

ALL REFERENCES CONSIDERED EXCEPT WHERE LINED THROUGH. /H.Le/



U.S. PCT Application Serial No: 10/553,994

Filed: October 20, 2005

Takamaro KIKKAWA, et al.

Docket No. 279784 US

#### STATEMENT OF RELEVANCY

- 1) References AO - AP & AW - AY have been cited in the International Search Report. A copy of these references is being submitted herewith.
- 2) References [redacted] have been cited in the corresponding [redacted] Search Report. A copy of these references is being submitted herewith.
- 3) References [redacted] are discussed in the specification. A copy of these references is being submitted herewith.
- 4) Reference AZ is additional prior art known to Applicant. A copy of this reference is being submitted herewith.